



INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION #16872Generic Copy

Issue Date: 29-Jun-2012**TITLE:** Product transfer from Unisem to Atp1 of LQFP 144L 20x20**PROPOSED FIRST SHIP DATE:** 29-Oct-2012**AFFECTED CHANGE CATEGORY(S):** Assembly location**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**Contact your local ON Semiconductor Sales Office or <Joh.Villanueva@onsemi.com>**NOTIFICATION TYPE:**

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change.


DESCRIPTION AND PURPOSE:

ON Semiconductor wish to inform its customers of the product transfer of LQFP 144L 20x20 from Unisem to Atp1 due to package discontinuance in Unisem. Unisem will be able support until December 2012 only.


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QUALIFICATION PLAN:

Estimated Date for Qualification Completion: 08/30/2012

Samples should be available after completion of Qualification.

 ON Semiconductor®											
Package Reliability Qualification Plan											
ON Product Name :						Qual Plan Revision :		A (QP120602)			
Customer Product Name :		BOLENO (Green of 504)				Date :		2/3/2012			
Maskset :		13505-523				Prepared by :		Gelo Ramos			
Package code & Type		BRD & LQFP				Approved by:					
Package & Assembly House :		AMKOR TECHNOLOGY PHILIPPINES				Fab/Process					
						Total parts required :		200			

ACCELERATED ENVIRONMENT STRESS TESTS											
Test #	Test	Reference	Test Conditions	Electrical Test Requirements	Sample Size per lot	Accept Criteria	# of Qual Lots	Total Parts Required for Qual Lots	# of Cntrl Lots	Total Parts Required for Control Lots	Comments
A1	Moisture Preconditioning (PC)	J-STD-020 & JESD22-A113	Moisture Soak (MSL = 3) Solder Reflow (3x @ 260°C)	Test @ room	77	0	1	77	1	77	Surface Mount Devices only. Preconditioning before tests A0 (SAT), A3 (AC/THU), A4 (TC). Test conditions are package dependent.
A0	Delamination check (SAT)	J-STD-020	Acoustic Microscopy	N.A.	ALL	0	1	ALL	1	77	Samples preconditioned per test A1 (PC)
A4	Temperature Cycling (TC)	JESD22-A104	-65°C to 150°C for 500 cycles	Test @ hot	77	0	1	77	1	77	Samples preconditioned per test A1 (PC). Test conditions are dependent on environment.
	Wire Bond Pull Strength (WBP)	MIL-STD883 Method 2011	Cond. C or D. Minimum pull strength after temperature cycle = 3 grams	N.A.	30 bonds from 5 parts	Cpk > 1.33 Ppk > 1.66 or 0 Fails after test A4 (TC)	1	5	1	5	DPA after TC.
PACKAGE ASSEMBLY INTEGRITY TESTS											
Test #	Test	Reference	Test Conditions	Electrical Test Requirements	Sample Size per lot	Accept Criteria	# of Qual Lots	Total Parts Required for Qual Lots	# of Cntrl Lots	Total Parts Required for Control Lots	Comments
	External Visual	Mil-Std-883D method 2009.		N.A.	ALL		ALL	ALL	ALL	ALL	Performed on all Parts

List of affected Customer Specific Parts:

 13505-523-XTD
 62022-001-XTD
 62268-001-XTD